	2015042000	0		Ρ	CN Da	te:	04/22/2014
Title: Datasheet u	update for TMP7	5/TMP175					
Customer Contact:	PCN Manager				t:	Quality Services	
Change Type:							
Assembly Site		Design			Wafer		
Assembly Proces		Data Sheet		\square	Wafer Bump Material		
Assembly Materials		Part number of	change	닐	Wafer Bump Process		
Mechanical Specification Packing/Shipping/Labeling		Test Site		H	Wafer Fab Site Wafer Fab Materials		
	J/Labeling	Test Process		H			Process
		PCN Deta	ils		warer	Tub	100035
Description of Chan	ige:	i chi betta					
Texas Instruments In The product datashee The following change	et(s) is being up	dated as summa	rized below.	7 1101		<i>i</i>	XAS
TMP175, TMP75					•		STRUMENTS
SBOS288K-JANUARY 2004-REV	ISED APRIL 2015						www.ti.com
Changes from Revision J (I	December 2007) to F	evision K					Page
section, Power Supply Re Mechanical, Packaging, a	ecommendations sect and Orderable Informa	on, Layout section, D ntion section.		entatio	on Suppo	rt secti	on, and 1
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th The datasheet numbe	ecommendations sect and Orderable Informa ae Timing Requiremer	ion, <i>Layout</i> section, <i>D</i> tion section tts table	evice and Docume	entatio	on Suppo	rt secti	on, and 1 6
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th The datasheet numbe Device Family	ecommendations sect and Orderable Informa ae Timing Requiremer	ion, <i>Layout</i> section, <i>D</i> ation section. Its table. Ing. Change From	evice and Docume	entatio	on Suppo	rt secti Char	on, and 1 <u>6</u> Ige To:
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th The datasheet numbe	ecommendations sect and Orderable Informa ae Timing Requiremer	ion, <i>Layout</i> section, <i>D</i> tion section tts table	evice and Docume	entatio	on Suppo	rt secti Char	on, and 1 6
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the roduct/tmp175 roduct/tmp75	ion, <i>Layout</i> section, <i>D</i> ation section. its table. Change From SBOS288J ne datasheet link	evice and Docume	entatio	on Suppo	rt secti Char	on, and 1 <u>6</u> Ige To:
section, Power Supply Re Mechanical, Packaging, a • Updated parameters in th The datasheet number Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr Reason for Changes To more accurately re	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 roduct/tmp75	ion, <i>Layout</i> section, <i>D</i> tion section. its table. Change From SBOS288J ne datasheet link racteristics.	n: ks provided.	entatio		Char SBO	on, and 1 <u>6</u> Ige To: S288K
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 oduct/tmp75 coduct/tmp75	ion, <i>Layout</i> section, <i>D</i> tion section. its table. Change From SBOS2883 ne datasheet link racteristics.	n: ks provided.	ility	(posit	Char SBO	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr Reason for Change: To more accurately re Anticipated impact No anticipated impact	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 coduct/tmp75 eflect device changer on Fit, Form, Fit. This is a speci	ion, <i>Layout</i> section, <i>D</i> tion section. its table. Change From SBOS288J ine datasheet link racteristics. Sunction, Quali fication change a	n: ks provided. ity or Reliab announcemer	ility	(posit	Char SBO	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr http://www.ti.com/pr Reason for Change: To more accurately re Anticipated impact No anticipated impact to the actual device. Changes to product	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 coduct/tmp75 eflect device changer on Fit, Form, Fit. This is a speci	ion, <i>Layout</i> section, <i>D</i> tion section. its table. Change From SBOS288J ine datasheet link racteristics. Sunction, Quali fication change a	n: ks provided. ity or Reliab announcemer	ility	(posit	Char SBO	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr Reason for Change: To more accurately re Anticipated impact	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 coduct/tmp75 eflect device changer on Fit, Form, Fit. This is a speci	ion, <i>Layout</i> section, <i>D</i> tion section. its table. Change From SBOS288J ine datasheet link racteristics. Sunction, Quali fication change a	n: ks provided. ity or Reliab announcemer	ility	(posit	Char SBO	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr http://www.ti.com/pr Reason for Change: To more accurately re Anticipated impact No anticipated impact to the actual device. Changes to product None. Product Affected:	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 oduct/tmp75 efflect device change on Fit, Form, Fit. This is a specific tidentification	ion, <i>Layout</i> section, <i>D</i> tion section. Its table. Change From SBOS288J ine datasheet link racteristics. Sunction, Quali fication change a	n: (s provided. (ty or Reliab announcemer h this PCN:	ility nt on	(posit	Char SBO	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr Reason for Changes To more accurately re Anticipated impact No anticipated impact to the actual device. Changes to product None. Product Affected: TMP175AID	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 oduct/tmp75 efflect device changen on Fit, Form, Fit. This is a specific tidentification TMP175AI	ion, <i>Layout</i> section, <i>D</i> tion section. Its table. Change From SBOS2883 ne datasheet link racteristics. Sunction, Quali fication change a resulting from	n: (s provided. ity or Reliab announcemer h this PCN: TMP75AIDG4	ility nt on	(posit	tive ar	on, and
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr http://www.ti.com/pr Reason for Change: To more accurately re Anticipated impact No anticipated impact to the actual device. Changes to product None. Product Affected: TMP175AID TMP175AID TMP175AID	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 oduct/tmp75 coduct/tmp75 effect device cha on Fit, Form, F t. This is a specific tidentification TMP175AI TMP175AI	ion, <i>Layout</i> section, <i>D</i> tion section. Its table. Change From SBOS288J ine datasheet link racteristics. Sunction, Quali fication change a resulting from DGKTG4	n: ty or Reliab announcemer this PCN: TMP75AIDG4 TMP75AIDG4	ility nt on	(posit	Char SBO tive , ere ar	on, and 1 6 1 1 6 1 1 6 1 1 6 1 1 1 6 1 1 1 1
section, Power Supply Re Mechanical, Packaging, a Updated parameters in th Device Family TMP75/TMP175 These changes may b http://www.ti.com/pr http://www.ti.com/pr Reason for Changes To more accurately re Anticipated impact No anticipated impact to the actual device. Changes to product None. Product Affected: TMP175AID	ecommendations sect and Orderable Informa- ne Timing Requirement er will be changin be reviewed at the oduct/tmp175 oduct/tmp75 efflect device changen on Fit, Form, Fit. This is a specific tidentification TMP175AI	ion, <i>Layout</i> section, <i>D</i> ition section. its table. Change From SBOS2883 ine datasheet link racteristics. Sunction, Quali fication change a resulting from DGKTG4 DR DR DRG4	n: (s provided. ity or Reliab announcemer h this PCN: TMP75AIDG4	ility nt on R RG4	(posit	Char SBO tive , ere ar	on, and

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com